



Material Content Data Sheet



Sales Product Name				BSZ058N03LS G		Issued		27. September 2017	
MA#				MA000896760					
Package				PG-TSDSON-8-22		Weight*		37.20 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.076	2.89	2.89	28937	28937	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		64		
	non noble metal	zinc	7440-66-6	0.009	0.03		255		
	non noble metal	iron	7439-89-6	0.189	0.51		5090		
wire	non noble metal	copper	7440-50-8	7.689	20.67	21.22	206692	212101	
	noble metal	gold	7440-57-5	0.202	0.54	0.54	5435	5435	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.10		1028	
plastics	plastics	epoxy resin	-	1.969	5.29		52925		
	inorganic material	silicondioxide	60676-86-0	17.108	46.01	51.40	459881	513834	
leadfinish	non noble metal	tin	7440-31-5	0.370	0.99	0.99	9948	9948	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2172	2172	
solder	non noble metal	tin	7440-31-5	0.064	0.17		1727		
	non noble metal	lead	7439-92-1	1.221	3.28	3.45	32814	34541	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		105		
	non noble metal	iron	7439-89-6	0.078	0.21		2106		
	non noble metal	copper	7440-50-8	3.182	8.55	8.77	85532	87769	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32		
	non noble metal	zinc	7440-66-6	0.005	0.01		126		
	non noble metal	iron	7439-89-6	0.094	0.25		2526		
	non noble metal	copper	7440-50-8	3.816	10.26	10.52	102579	105263	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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